

## N - CHANNEL ENHANCEMENT MODE FAST POWER MOS TRANSISTOR

PRELIMINARY DATA

| TYPE      | V <sub>DSS</sub> | R <sub>DS(on)</sub> | I <sub>D</sub> |
|-----------|------------------|---------------------|----------------|
| STU14NA50 | 500 V            | < 0.36 Ω            | 14 A           |

- TYPICAL R<sub>DS(on)</sub> = 0.31 Ω
- EFFICIENT AND RELIABLE MOUNTING THROUGH CLIP
- ± 30V GATE TO SOURCE VOLTAGE RATING
- REPETITIVE AVALANCHE TESTED
- LOW INTRINSIC CAPACITANCE
- 100% AVALANCHE TESTED
- GATE CHARGE MINIMIZED
- REDUCED THRESHOLD VOLTAGE SPREAD

### DESCRIPTION

The Max220™ package is a new high volume power package exhibiting the same footprint as the industry standard TO-220, but designed to accommodate much larger silicon chips, normally supplied in bigger packages. The increased die capacity makes the device ideal to reduce component count in multiple paralleled TO-220 designs and save board space with respect to larger packages.

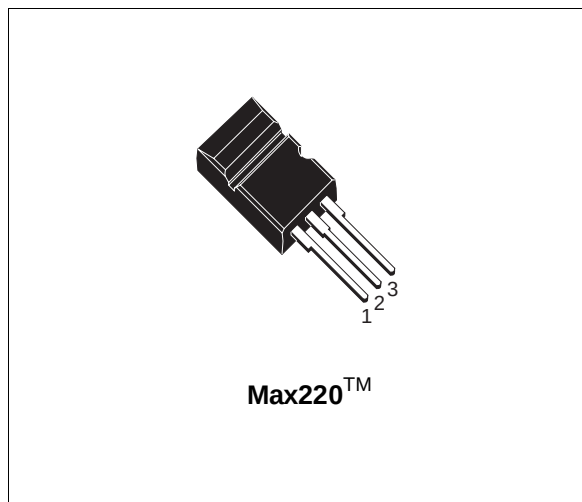
### APPLICATIONS

- HIGH CURRENT, HIGH SPEED SWITCHING
- SWITCH MODE POWER SUPPLIES (SMPS)
- DC-AC CONVERTERS FOR WELDING EQUIPMENT AND UNINTERRUPTIBLE POWER SUPPLIES (UPS)

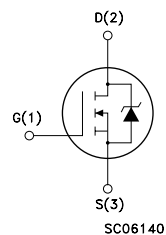
### ABSOLUTE MAXIMUM RATINGS

| Symbol              | Parameter                                             | Value      | Unit |
|---------------------|-------------------------------------------------------|------------|------|
| V <sub>DS</sub>     | Drain-source Voltage (V <sub>GS</sub> = 0)            | 500        | V    |
| V <sub>DGR</sub>    | Drain- gate Voltage (R <sub>GS</sub> = 20 kΩ)         | 500        | V    |
| V <sub>GS</sub>     | Gate-source Voltage                                   | ± 30       | V    |
| I <sub>D</sub>      | Drain Current (continuous) at T <sub>c</sub> = 25 °C  | 14         | A    |
| I <sub>D</sub>      | Drain Current (continuous) at T <sub>c</sub> = 100 °C | 8.8        | A    |
| I <sub>DM</sub> (•) | Drain Current (pulsed)                                | 56         | A    |
| P <sub>tot</sub>    | Total Dissipation at T <sub>c</sub> = 25 °C           | 160        | W    |
|                     | Derating Factor                                       | 1.28       | W/°C |
| T <sub>stg</sub>    | Storage Temperature                                   | -65 to 150 | °C   |
| T <sub>j</sub>      | Max. Operating Junction Temperature                   | 150        | °C   |

(•) Pulse width limited by safe operating area



### INTERNAL SCHEMATIC DIAGRAM



**THERMAL DATA**

|                |                                                |     |      |               |
|----------------|------------------------------------------------|-----|------|---------------|
| $R_{thj-case}$ | Thermal Resistance Junction-case               | Max | 0.78 | $^{\circ}C/W$ |
| $R_{thj-amb}$  | Thermal Resistance Junction-ambient            | Max | 62.5 | $^{\circ}C/W$ |
| $R_{thc-sink}$ | Thermal Resistance Case-sink                   | Typ | 0.5  | $^{\circ}C/W$ |
| $T_l$          | Maximum Lead Temperature For Soldering Purpose |     | 300  | $^{\circ}C$   |

**AVALANCHE CHARACTERISTICS**

| Symbol   | Parameter                                                                                                                   | Max Value | Unit |
|----------|-----------------------------------------------------------------------------------------------------------------------------|-----------|------|
| $I_{AR}$ | Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by $T_j$ max, $\delta < 1\%$ )                         | 14        | A    |
| $E_{AS}$ | Single Pulse Avalanche Energy (starting $T_j = 25^{\circ}C$ , $I_D = I_{AR}$ , $V_{DD} = 50$ V)                             | 980       | mJ   |
| $E_{AR}$ | Repetitive Avalanche Energy (pulse width limited by $T_j$ max, $\delta < 1\%$ )                                             | 39        | mJ   |
| $I_{AR}$ | Avalanche Current, Repetitive or Not-Repetitive ( $T_c = 100^{\circ}C$ , pulse width limited by $T_j$ max, $\delta < 1\%$ ) | 8.8       | A    |

**ELECTRICAL CHARACTERISTICS** ( $T_{case} = 25^{\circ}C$  unless otherwise specified)

**OFF**

| Symbol        | Parameter                                        | Test Conditions                                                                              | Min. | Typ. | Max.      | Unit               |
|---------------|--------------------------------------------------|----------------------------------------------------------------------------------------------|------|------|-----------|--------------------|
| $V_{(BR)DSS}$ | Drain-source Breakdown Voltage                   | $I_D = 250 \mu A$ $V_{GS} = 0$                                                               | 500  |      |           | V                  |
| $I_{DSS}$     | Zero Gate Voltage Drain Current ( $V_{GS} = 0$ ) | $V_{DS} = \text{Max Rating}$<br>$V_{DS} = \text{Max Rating} \times 0.8$ $T_c = 100^{\circ}C$ |      |      | 25<br>50  | $\mu A$<br>$\mu A$ |
| $I_{GSS}$     | Gate-body Leakage Current ( $V_{DS} = 0$ )       | $V_{GS} = \pm 30$ V                                                                          |      |      | $\pm 100$ | nA                 |

**ON (\*)**

| Symbol       | Parameter                         | Test Conditions                                                                 | Min. | Typ. | Max.         | Unit                 |
|--------------|-----------------------------------|---------------------------------------------------------------------------------|------|------|--------------|----------------------|
| $V_{GS(th)}$ | Gate Threshold Voltage            | $V_{DS} = V_{GS}$ $I_D = 250 \mu A$                                             | 2.25 | 3    | 3.75         | V                    |
| $R_{DS(on)}$ | Static Drain-source On Resistance | $V_{GS} = 10$ V $I_D = 7$ A<br>$V_{GS} = 10$ V $I_D = 7$ A $T_c = 100^{\circ}C$ |      | 0.31 | 0.36<br>0.72 | $\Omega$<br>$\Omega$ |
| $I_{D(on)}$  | On State Drain Current            | $V_{DS} > I_{D(on)} \times R_{DS(on)max}$<br>$V_{GS} = 10$ V                    | 14   |      |              | A                    |

**DYNAMIC**

| Symbol       | Parameter                    | Test Conditions                                       | Min. | Typ. | Max. | Unit |
|--------------|------------------------------|-------------------------------------------------------|------|------|------|------|
| $g_{fs} (*)$ | Forward Transconductance     | $V_{DS} > I_{D(on)} \times R_{DS(on)max}$ $I_D = 7$ A | 8.5  | 11   |      | S    |
| $C_{iss}$    | Input Capacitance            | $V_{DS} = 25$ V $f = 1$ MHz $V_{GS} = 0$              |      | 2750 | 3600 | pF   |
| $C_{oss}$    | Output Capacitance           |                                                       |      | 380  | 500  | pF   |
| $C_{rss}$    | Reverse Transfer Capacitance |                                                       |      | 105  | 140  | pF   |

**ELECTRICAL CHARACTERISTICS** (continued)**SWITCHING ON**

| Symbol                        | Parameter                                                    | Test Conditions                                                                          | Min. | Typ.            | Max.     | Unit           |
|-------------------------------|--------------------------------------------------------------|------------------------------------------------------------------------------------------|------|-----------------|----------|----------------|
| $t_{d(on)}$<br>$t_r$          | Turn-on Time<br>Rise Time                                    | $V_{DD} = 250\text{ V}$ $I_D = 7\text{ A}$<br>$R_G = 4.7\ \Omega$ $V_{GS} = 10\text{ V}$ |      | 36<br>53        | 48<br>70 | ns<br>ns       |
| $(di/dt)_{on}$                | Turn-on Current Slope                                        | $V_{DD} = 400\text{ V}$ $I_D = 14\text{ A}$<br>$R_G = 47\ \Omega$ $V_{GS} = 10\text{ V}$ |      | 160             |          | A/ $\mu$ s     |
| $Q_g$<br>$Q_{gs}$<br>$Q_{gd}$ | Total Gate Charge<br>Gate-Source Charge<br>Gate-Drain Charge | $V_{DD} = 400\text{ V}$ $I_D = 14\text{ A}$ $V_{GS} = 10\text{ V}$                       |      | 115<br>16<br>53 | 150      | nC<br>nC<br>nC |

**SWITCHING OFF**

| Symbol                          | Parameter                                             | Test Conditions                                                                           | Min. | Typ.           | Max.            | Unit           |
|---------------------------------|-------------------------------------------------------|-------------------------------------------------------------------------------------------|------|----------------|-----------------|----------------|
| $t_{r(Voff)}$<br>$t_f$<br>$t_c$ | Off-voltage Rise Time<br>Fall Time<br>Cross-over Time | $V_{DD} = 400\text{ V}$ $I_D = 14\text{ A}$<br>$R_G = 4.7\ \Omega$ $V_{GS} = 10\text{ V}$ |      | 52<br>24<br>80 | 68<br>32<br>105 | ns<br>ns<br>ns |

**SOURCE DRAIN DIODE**

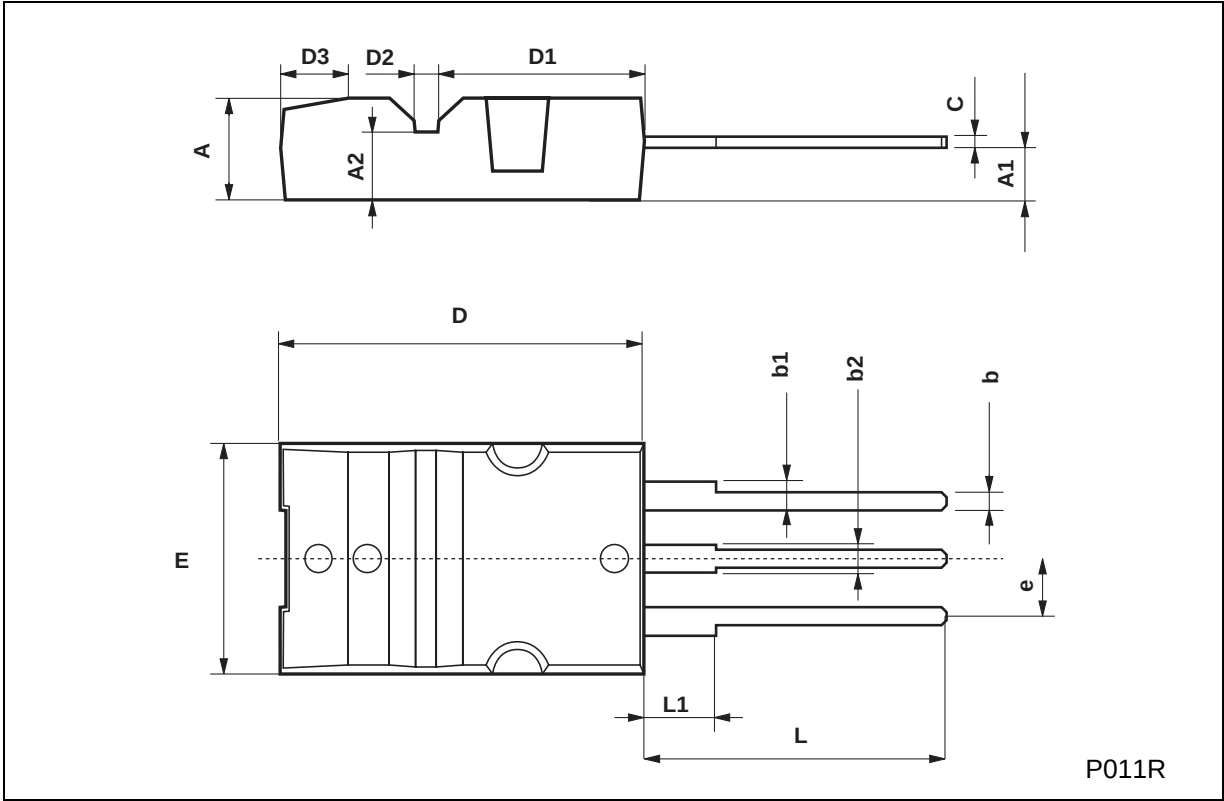
| Symbol                            | Parameter                                                                    | Test Conditions                                                                                                        | Min. | Typ.              | Max.     | Unit                     |
|-----------------------------------|------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------|------|-------------------|----------|--------------------------|
| $I_{SD}$<br>$I_{SDM}(\bullet)$    | Source-drain Current<br>Source-drain Current (pulsed)                        |                                                                                                                        |      |                   | 14<br>56 | A<br>A                   |
| $V_{SD} (*)$                      | Forward On Voltage                                                           | $I_{SD} = 14\text{ A}$ $V_{GS} = 0$                                                                                    |      |                   | 1.6      | V                        |
| $t_{rr}$<br>$Q_{rr}$<br>$I_{RRM}$ | Reverse Recovery Time<br>Reverse Recovery Charge<br>Reverse Recovery Current | $I_{SD} = 14\text{ A}$ $di/dt = 100\text{ A}/\mu\text{s}$<br>$V_{DD} = 100\text{ V}$ $T_j = 150\text{ }^\circ\text{C}$ |      | 650<br>12.3<br>38 |          | ns<br>$\mu\text{C}$<br>A |

(\*) Pulsed: Pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5 %

(\bullet) Pulse width limited by safe operating area

Max220 MECHANICAL DATA

| DIM. | mm    |      |       | inch  |       |       |
|------|-------|------|-------|-------|-------|-------|
|      | MIN.  | TYP. | MAX.  | MIN.  | TYP.  | MAX.  |
| A    | 4.3   |      | 4.6   | 0.169 |       | 0.181 |
| A1   | 2.2   |      | 2.4   | 0.087 |       | 0.094 |
| A2   | 2.9   |      | 3.1   | 0.114 |       | 0.122 |
| b    | 0.7   |      | 0.93  | 0.027 |       | 0.036 |
| b1   | 1.25  |      | 1.4   | 0.049 |       | 0.055 |
| b2   | 1.2   |      | 1.38  | 0.047 |       | 0.054 |
| c    | 0.45  |      | 0.6   |       | 0.18  | 0.023 |
| D    | 15.9  |      | 16.3  |       | 0.626 | 0.641 |
| D1   | 9     |      | 9.35  | 0.354 |       | 0.368 |
| D2   | 0.8   |      | 1.2   | 0.031 |       | 0.047 |
| D3   | 2.8   |      | 3.2   | 0.110 |       | 0.126 |
| e    | 2.44  |      | 2.64  | 0.096 |       | 0.104 |
| E    | 10.05 |      | 10.35 | 0.396 |       | 0.407 |
| L    | 13.2  |      | 13.6  | 0.520 |       | 0.535 |
| L1   | 3     |      | 3.4   | 0.118 |       | 0.133 |



Information furnished is believed to be accurate and reliable. However, SGS-THOMSON Microelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of SGS-THOMSON Microelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. SGS-THOMSON Microelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of SGS-THOMSON Microelectronics.

© 1997 SGS-THOMSON Microelectronics - Printed in Italy - All Rights Reserved

SGS-THOMSON Microelectronics GROUP OF COMPANIES  
Australia - Brazil - Canada - China - France - Germany - Hong Kong - Italy - Japan - Korea - Malaysia - Malta - Morocco - The Netherlands -  
Singapore - Spain - Sweden - Switzerland - Taiwan - Thailand - United Kingdom - U.S.A  
...